

SCIENCES

Networks and Communications, Field Director – Guy Pujolle

Internet, Subject Head – Stefano Secci

The Tactile Internet

Coordinated by
Tara Ali-Yahiya
Wrya Monnet

Color Section

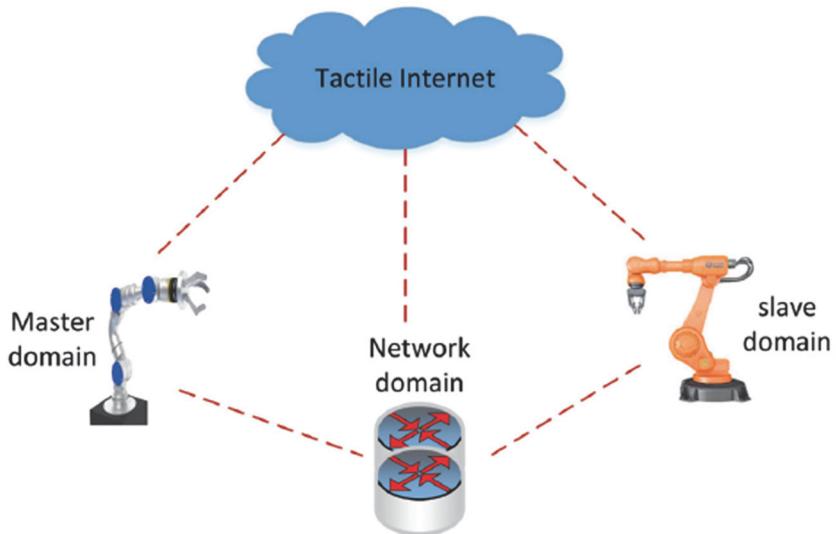


Figure 1.2. *Tactile Internet architecture*

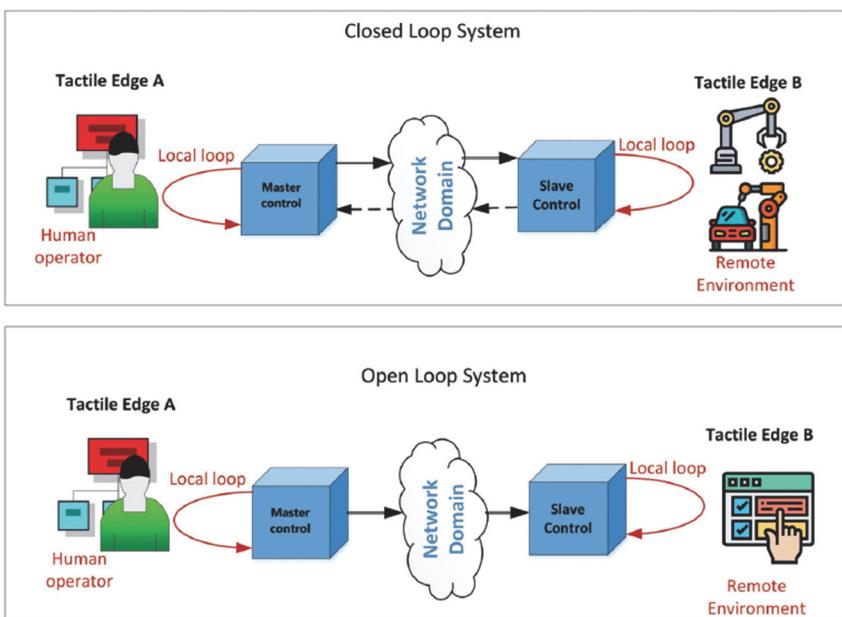


Figure 1.3. *Open-loop versus closed-loop systems*

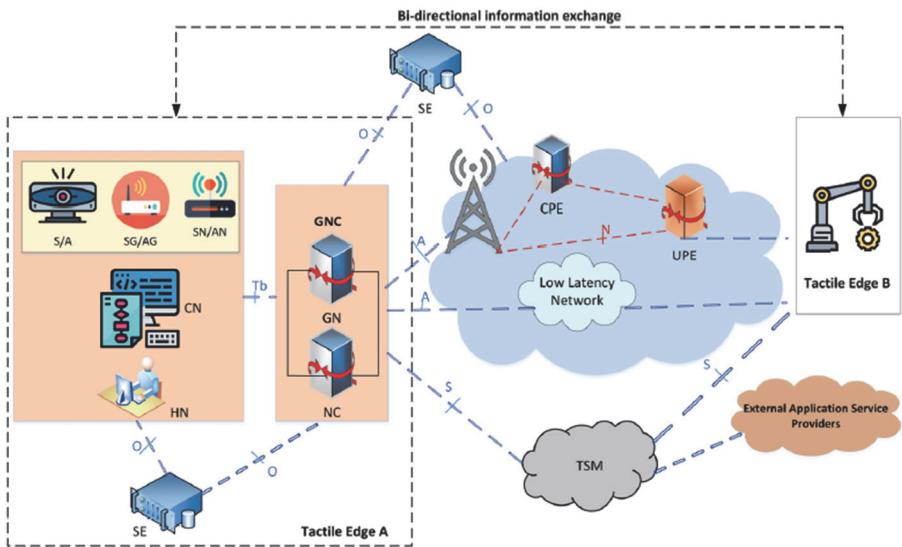


Figure 2.1. TI reference architecture of IEEE 1918.1

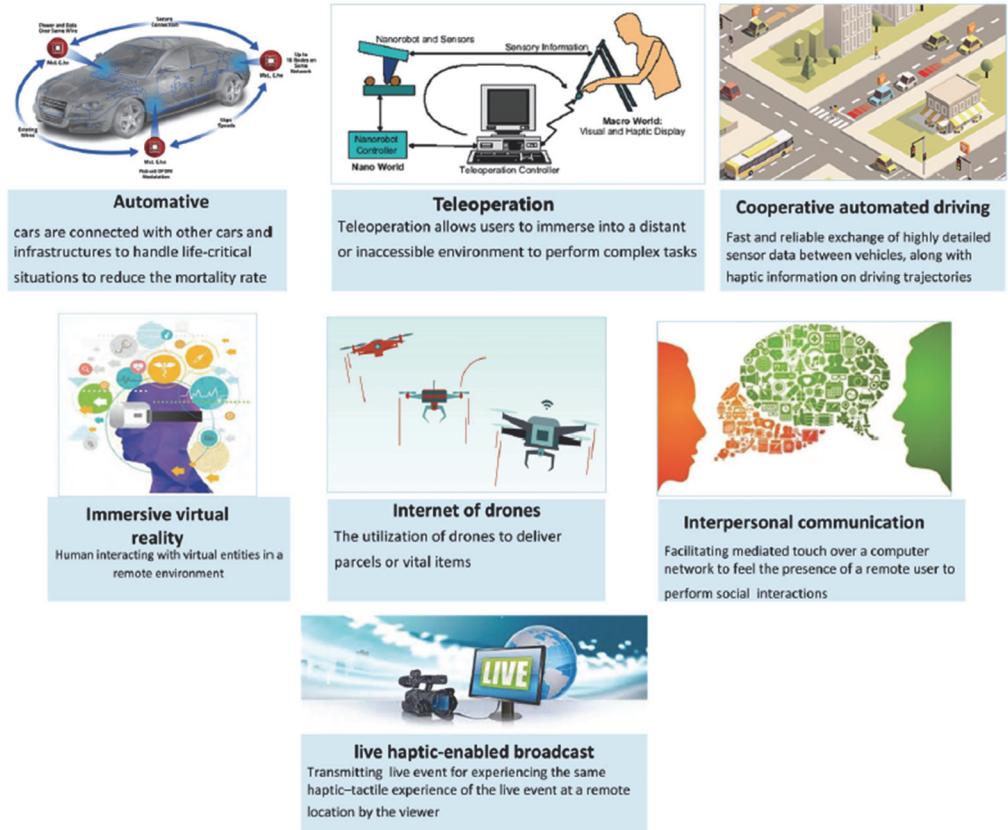


Figure 2.2. Tactile Internet use cases

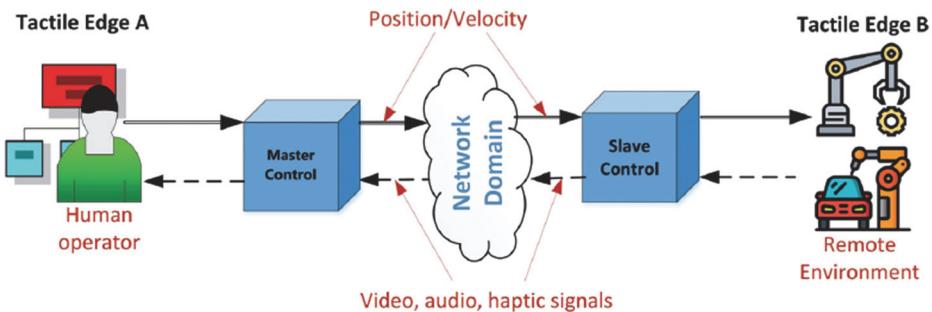


Figure 2.3. Teleoperation use cases

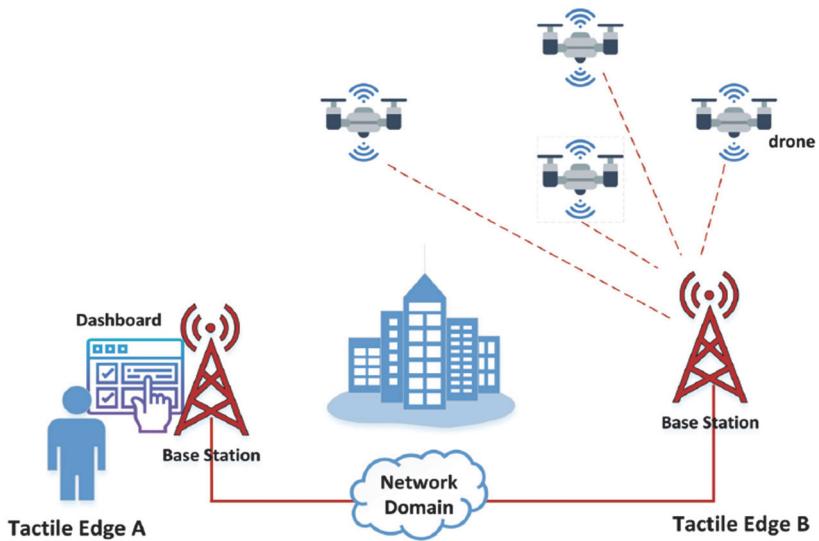


Figure 2.4. Internet of drones use case

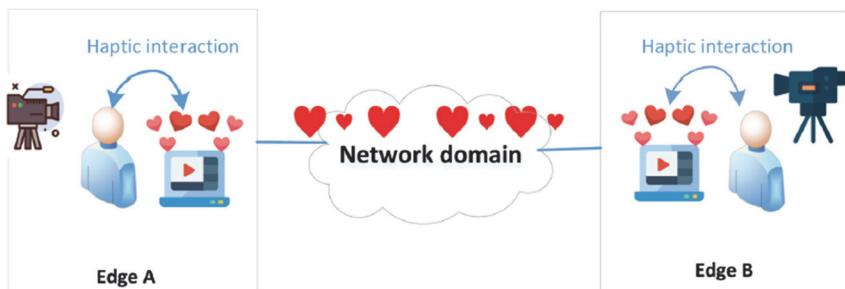


Figure 2.5. Interpersonal communication use cases

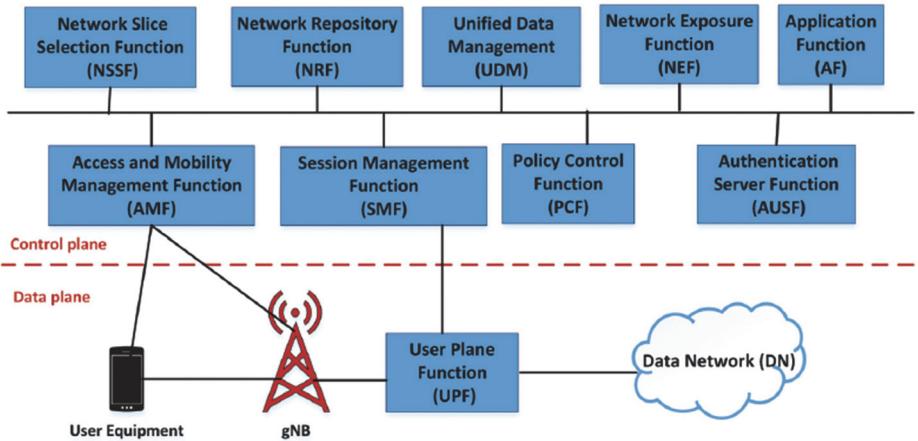


Figure 3.1. 5G architecture (ETSI 2018b)

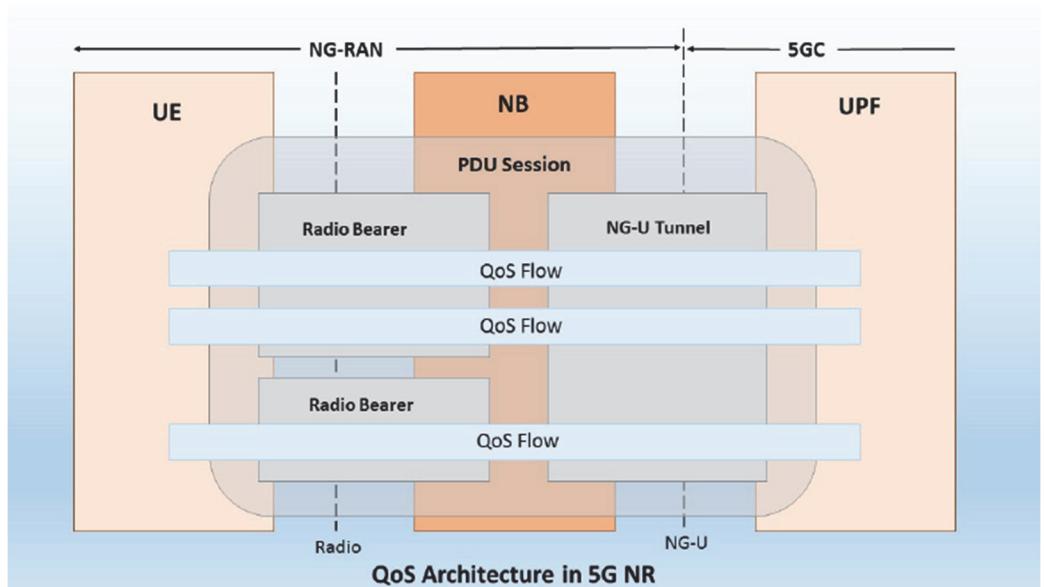


Figure 3.2. 5G QoS architecture

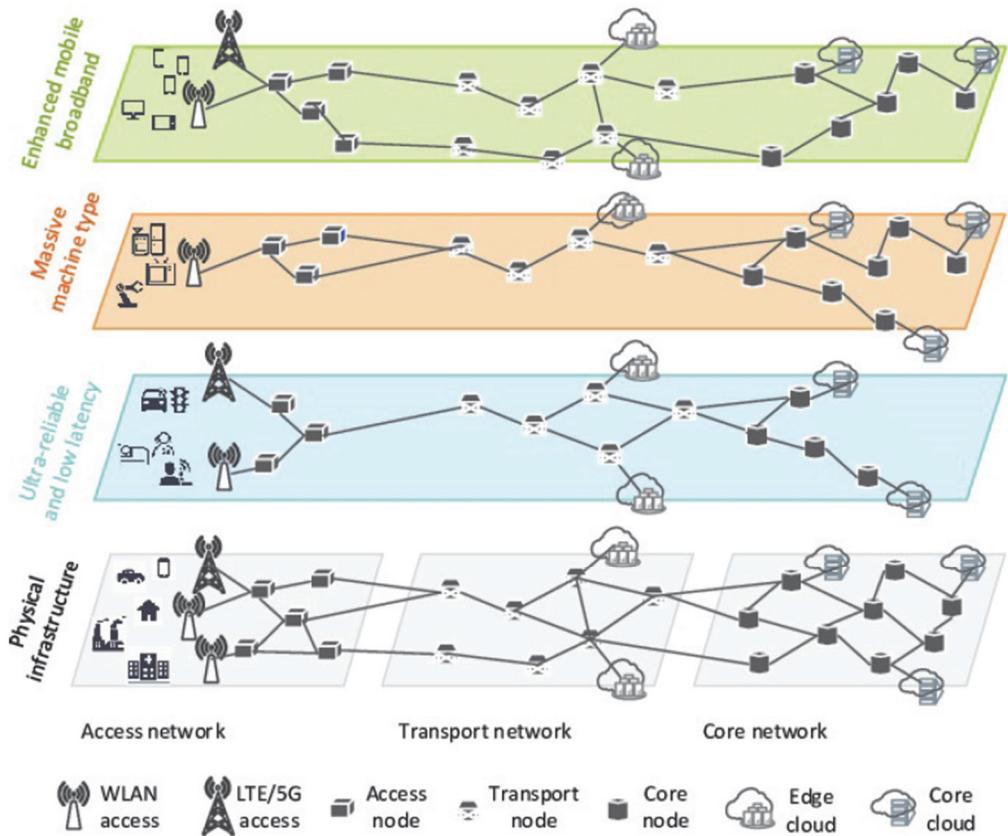


Figure 3.3. Network slicing (Rost et al. 2017)

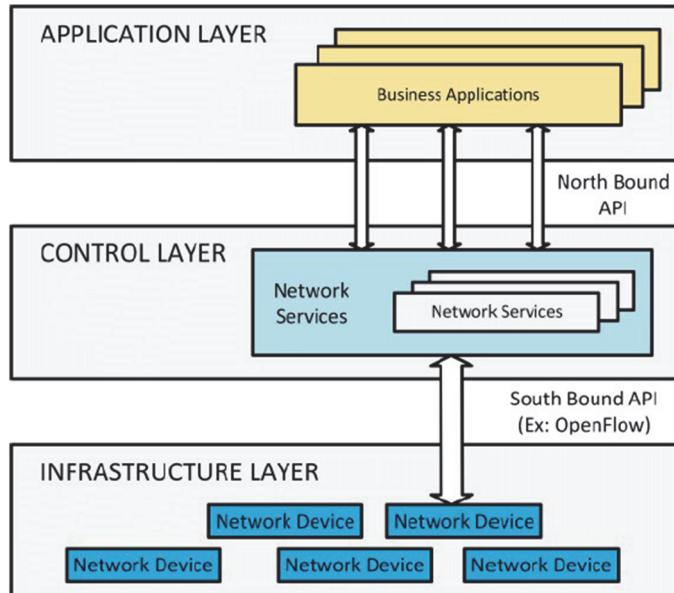


Figure 3.5. Software-defined networking (SDN)

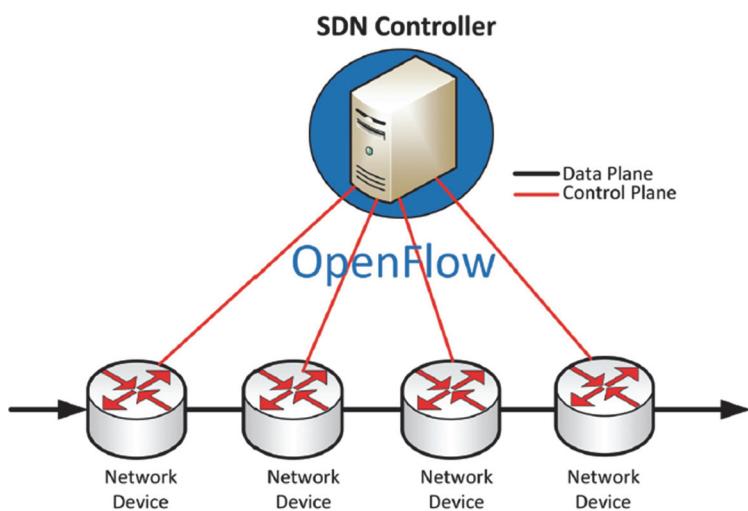


Figure 3.6. SDN with openflow

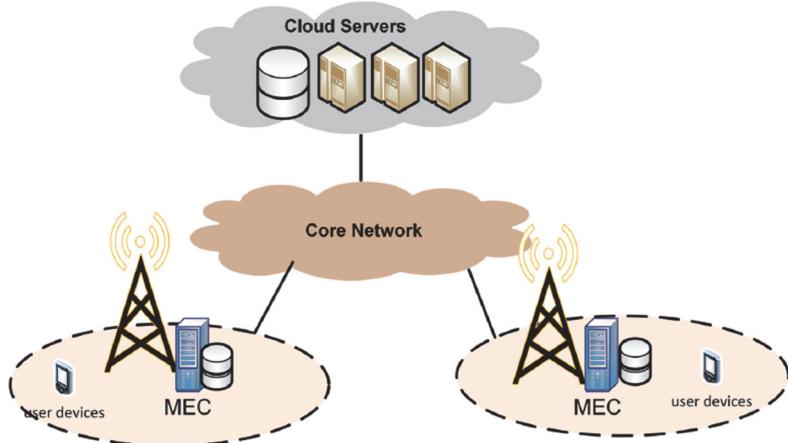


Figure 3.7. MEC integrated with 5G

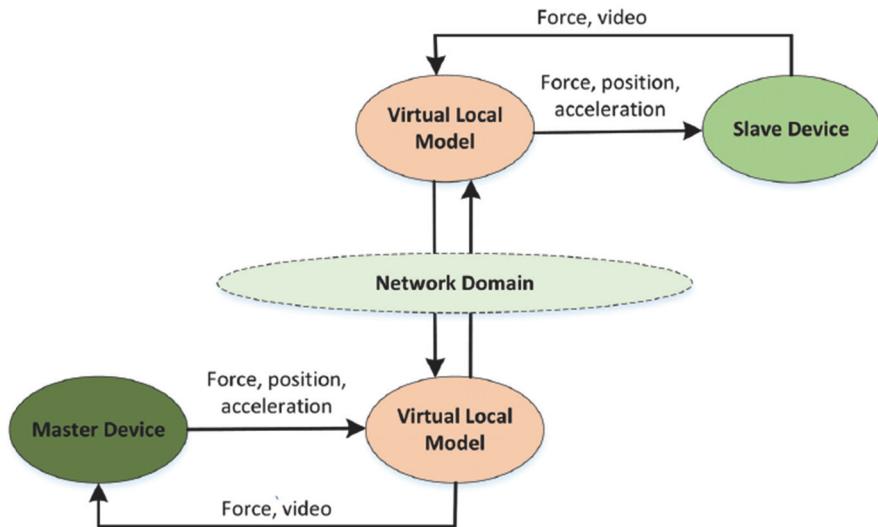


Figure 3.9. Model-mediated architecture

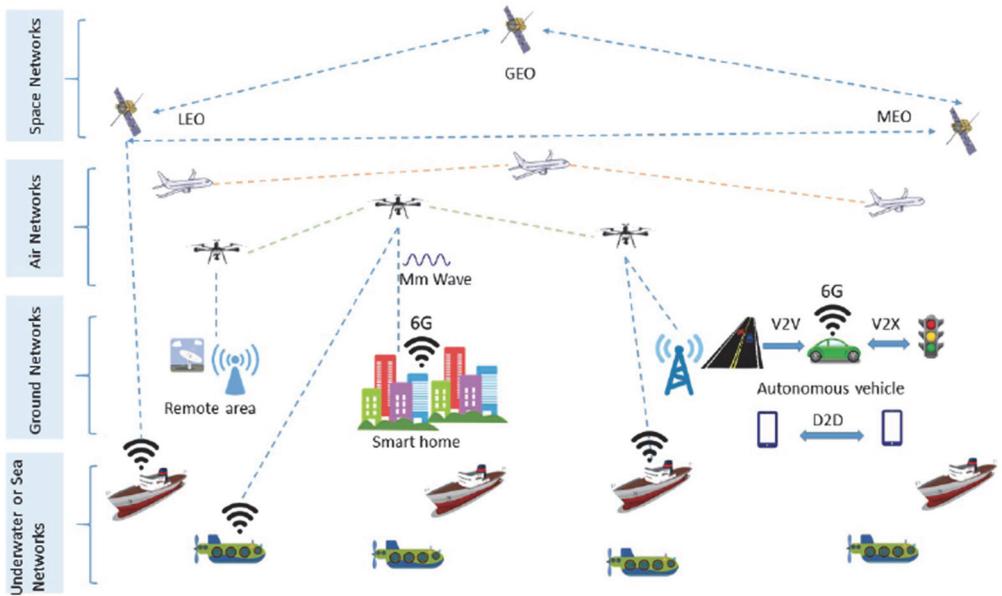


Figure 4.2. Architecture of 6G

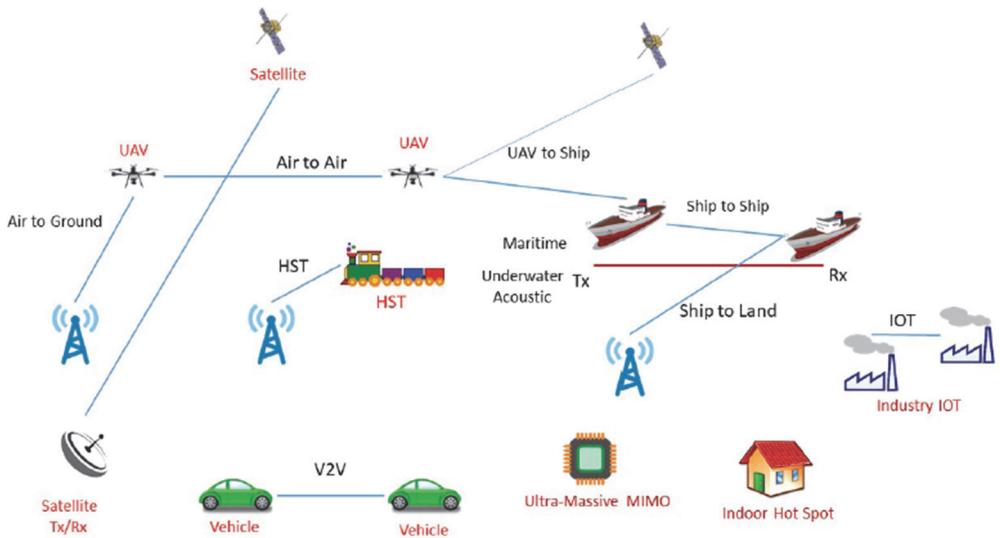


Figure 4.3. 6G wireless channels. Rx: receiver; Tx: transmitter

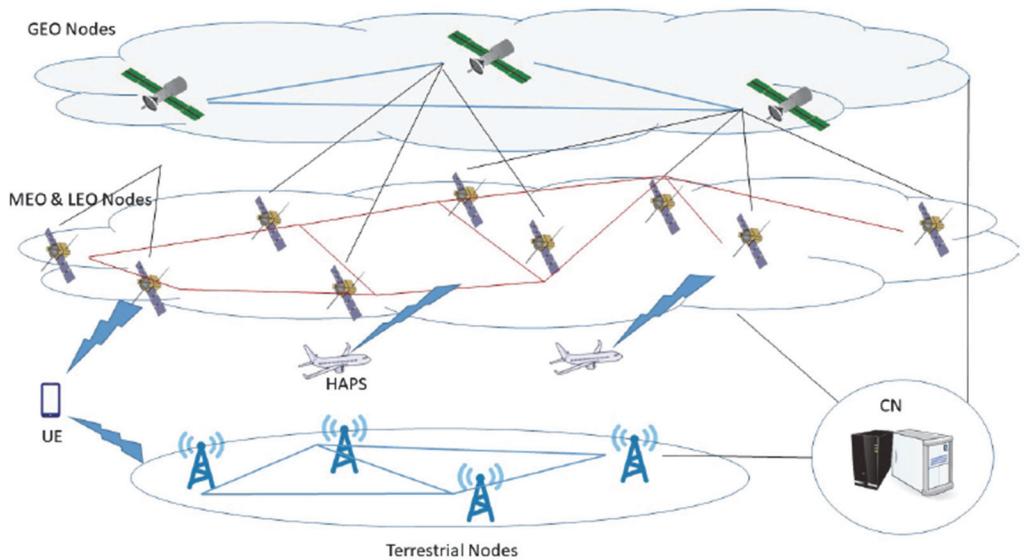


Figure 4.5. System architecture of the 6G system

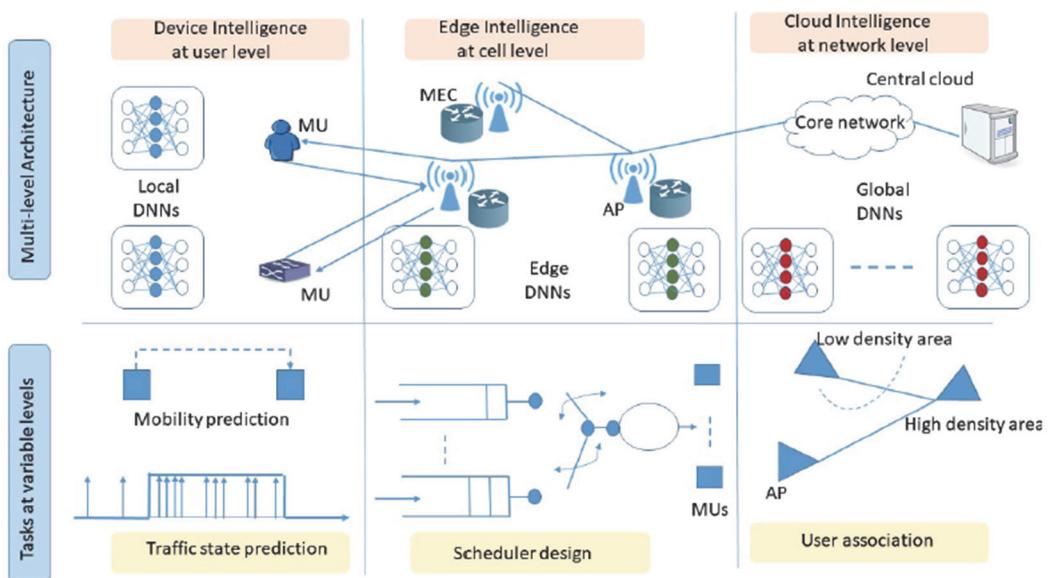


Figure 4.6. Multi-level architecture in 6G

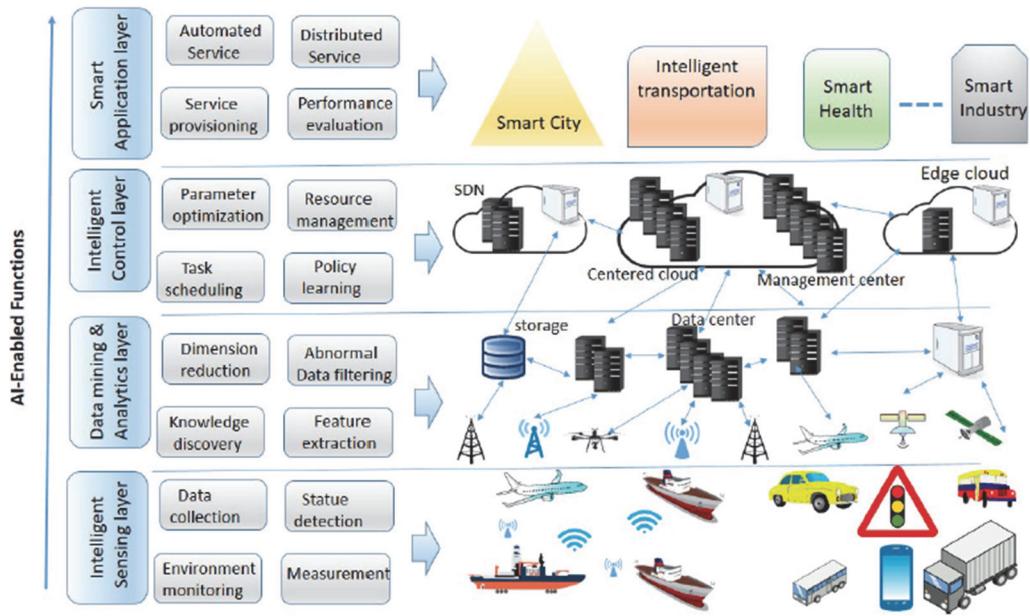


Figure 4.7. AI-enabled intelligent 6G networks

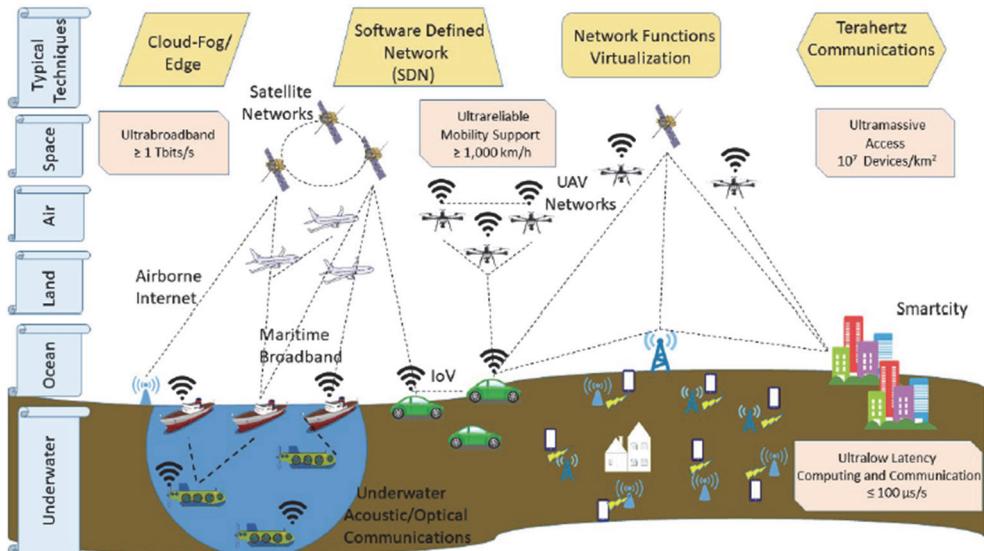


Figure 4.8. AI/ML applications in 6G to support ultra-broadband, ultra-massive access and ultra-reliability/low latency

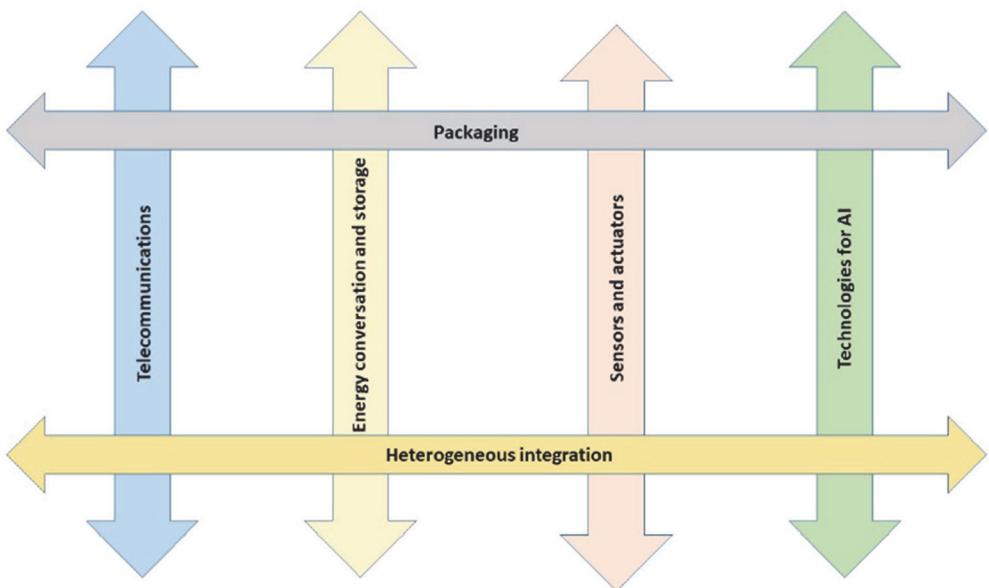


Figure 4.9. Schema of vertical and horizontal MEMS-based application domains relevant to the 6G and TI future development and deployment

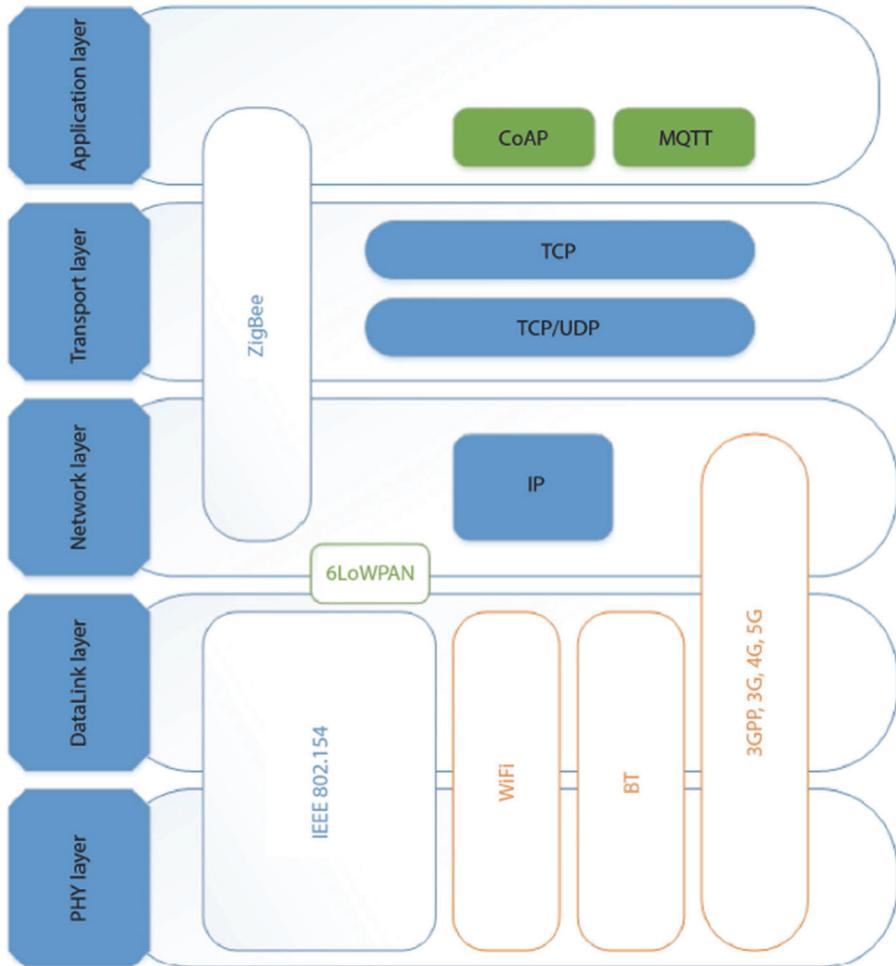


Figure 5.2. Five-layer IoT and its equivalent OSI layers

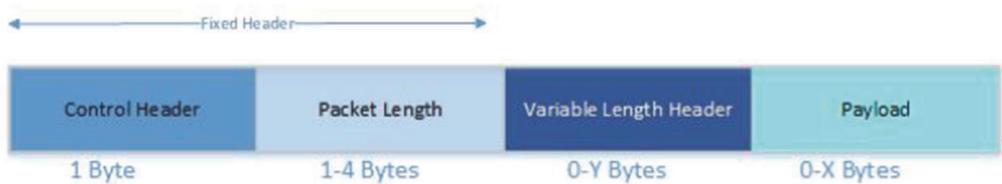


Figure 5.5. MQTT standard packet structure

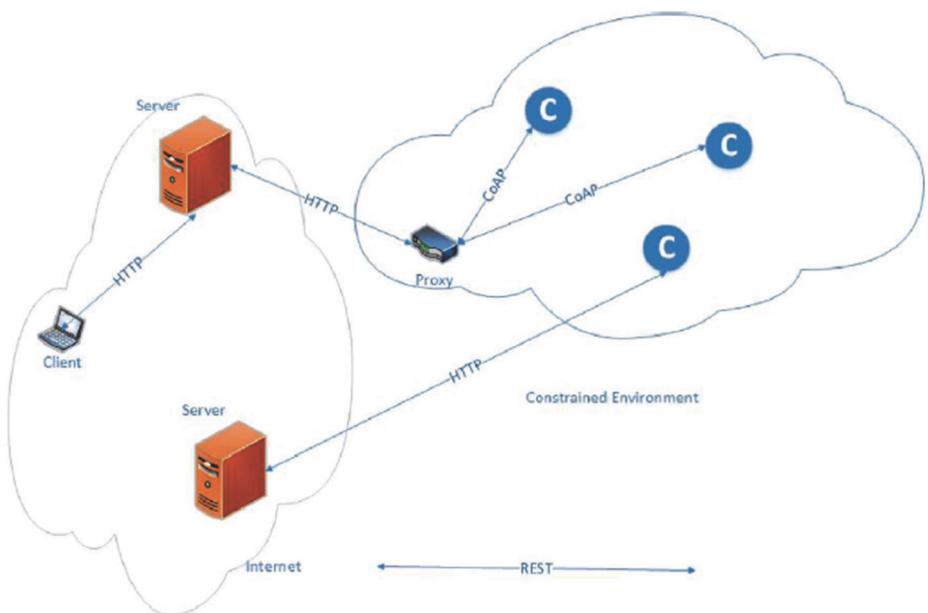


Figure 5.8. CoAP architecture

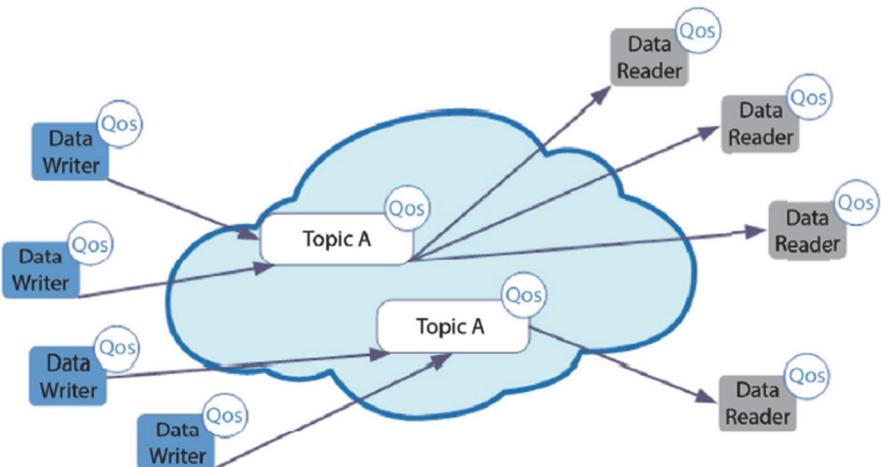


Figure 5.10. Architecture of a DDS protocol to connect applications systems

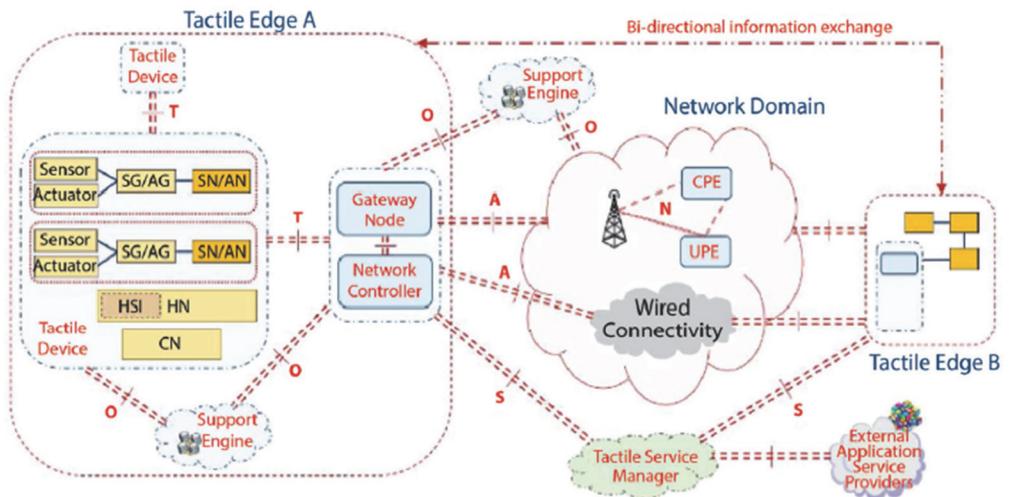


Figure 5.13. IEEE P1918 Tactile Internet reference architecture (Holland et al. 2019)

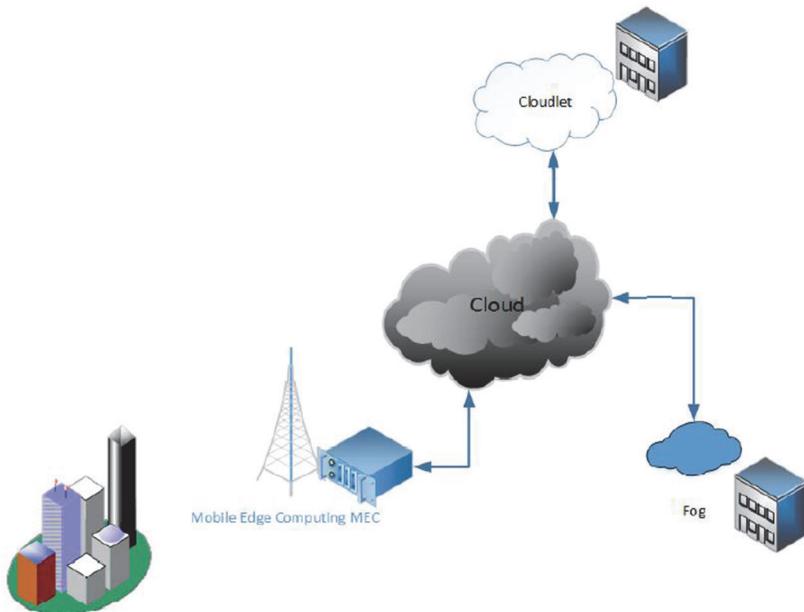


Figure 5.14. Edge computing in IoT systems

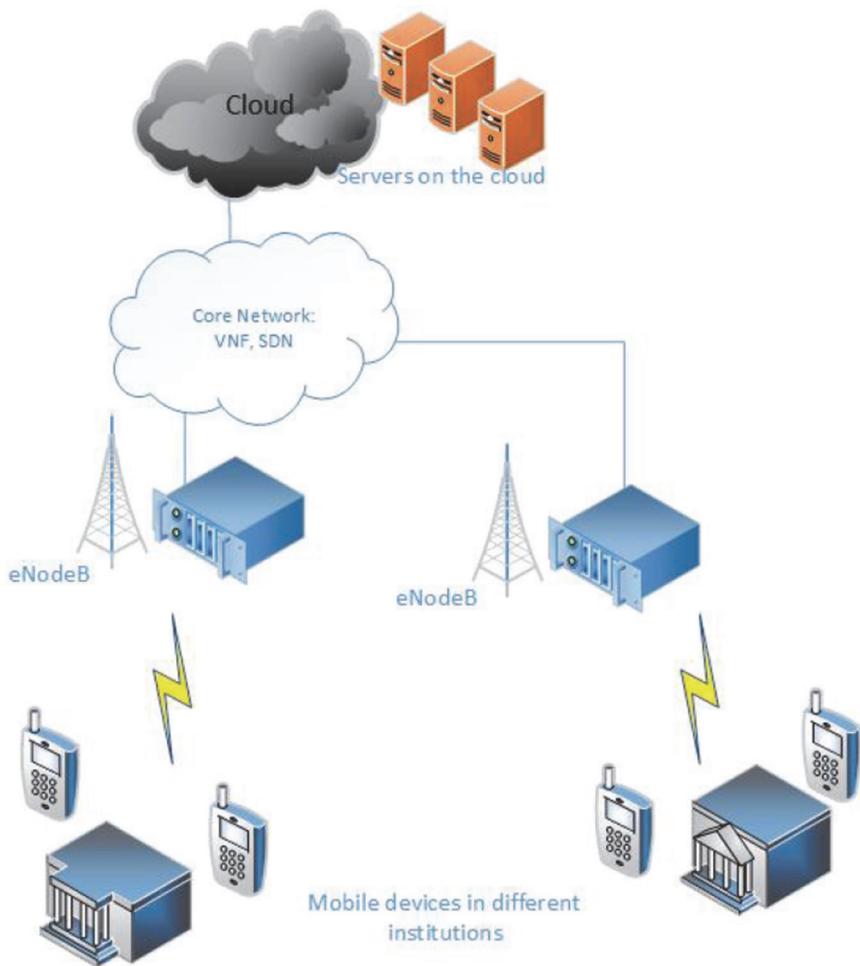


Figure 5.15. SDN and VNF in the core network and the MEC access to them

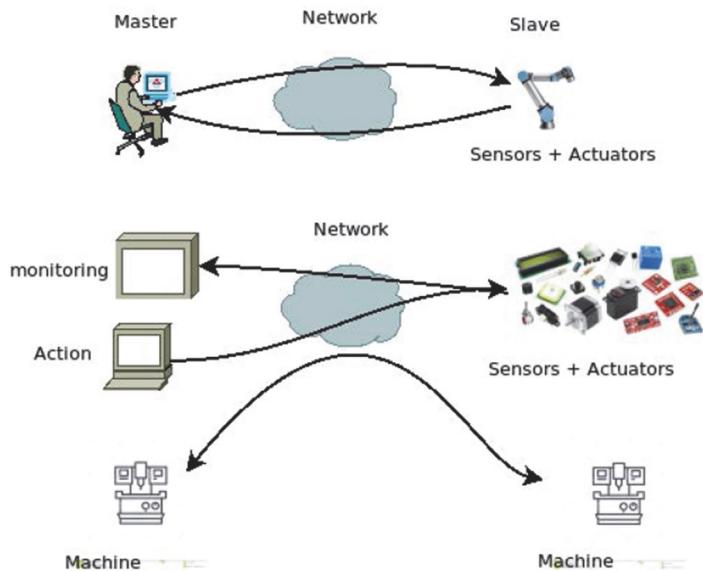


Figure 5.17. Communalities and differences between the IoT (bottom) and the TI (top)

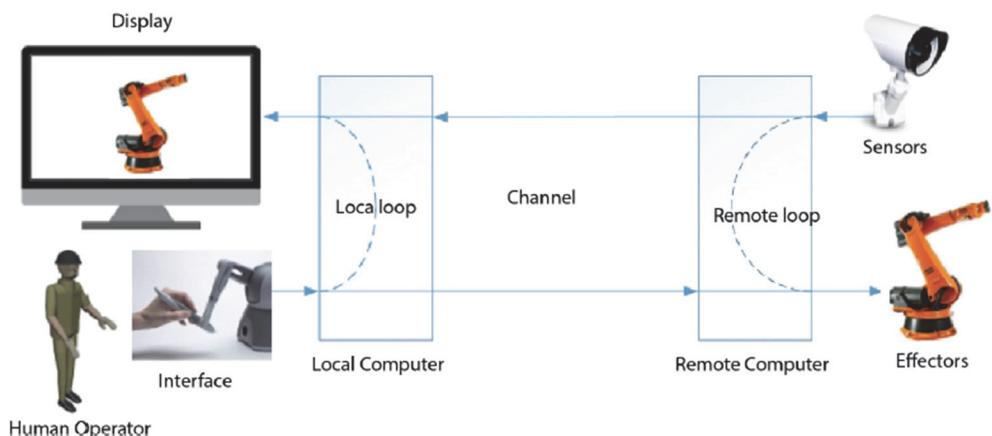


Figure 6.1. Telerobotics as first devised by Sheridan (Ferrell and Sheridan 1967)

<https://www.haption.com/fr/applications-fr/nuclear-fr.html>



Nature 27 September 2001



<https://www.saabseaeye.com/>



<https://www.identifiedtech.com/blog/uav-surveying/drone-technology-ending-the-drone-vs-uav-debate-drone-basics-101/>



<https://im-mining.com/2019/06/05/aridua-project-underground-mining-robot-julius-continues-yield-valuable-research-results/>

Figure 6.2. Different telepresence applications

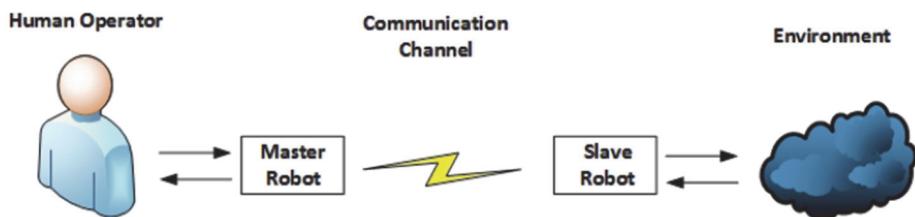


Figure 6.3. Components of a telerobotic

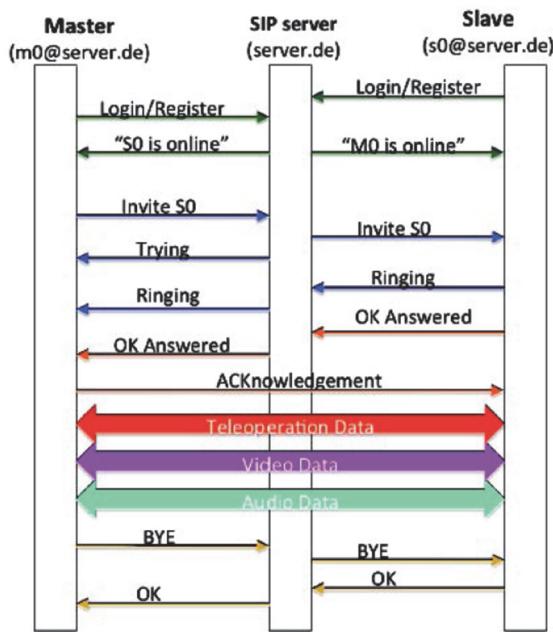


Figure 6.18. SIP master to slave call with both users addressed on the same server (source: King et al. 2010)



Figure 6.19. Twenty actuated DOF and a further four under-actuated movements for a total of 24 joints in a dexterous hand from The Shadow Robot Company (source: <https://www.shadowrobot.com/dexterous-hand-series/>)



Figure 6.20. Hapex glove contains haptic feedback. Connecting to the shadow robotic hand, it can mimic the glove movements (source: <https://haptx.com/robotics/>)

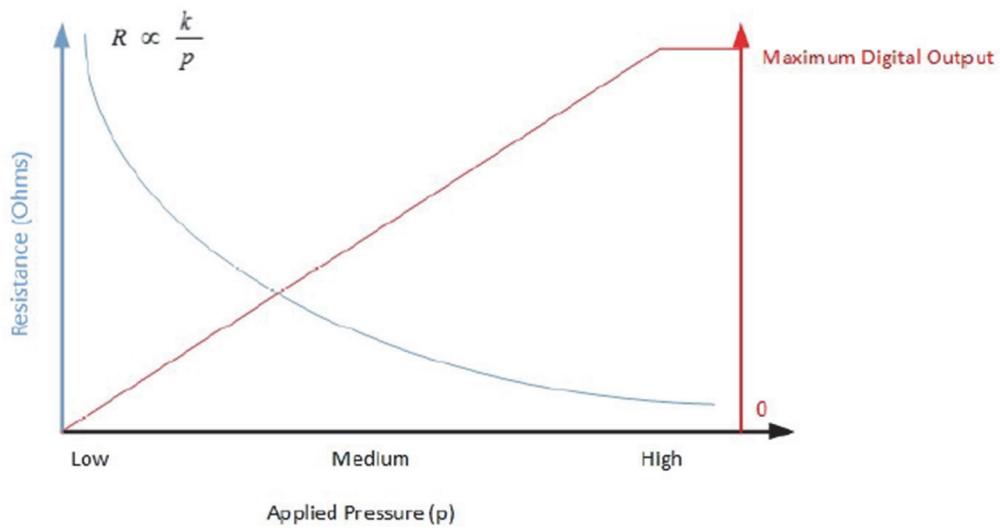


Figure 7.1. Piezoelectric resistance characteristic with applied pressure

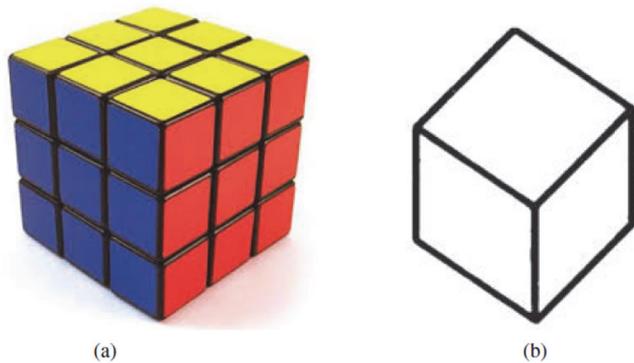


Figure 7.2. Two cubes: (a) is different in its local shapes from (b) which is smooth. Both are globally a cube

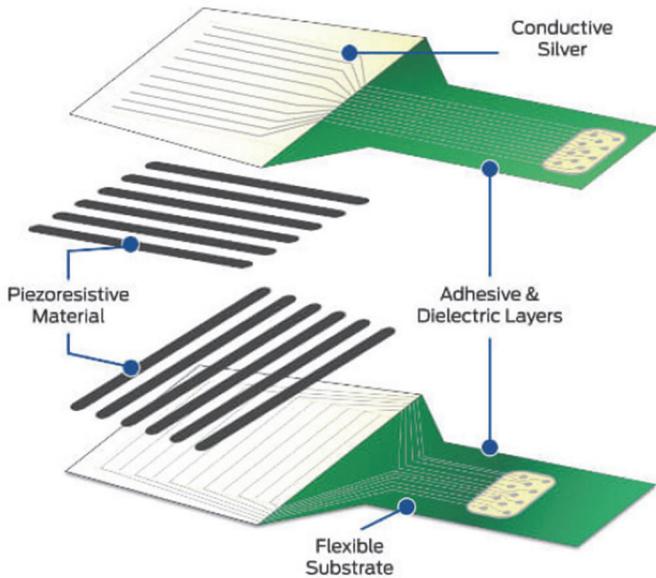


Figure 7.3. Thin tactile sensor technology from (<https://www.tekscan.com/>)



(a) Phantom Omni



(b) Novint Technologies Falcon



(c) Force Dimension Sigma 7



(d) Dexmo

Figure 7.4. Some commercially available haptic interface devices

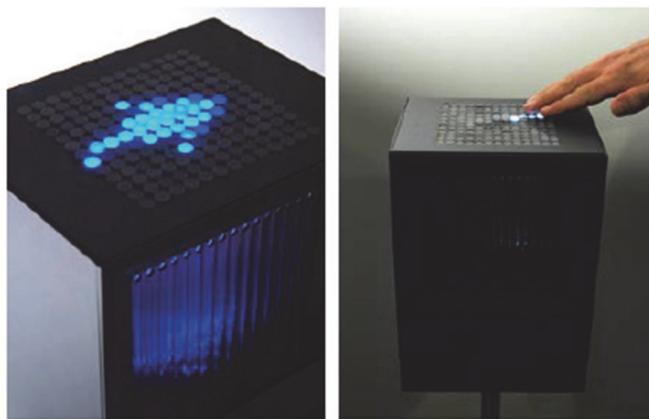


Figure 7.5. A tactile interface device: Lumen (Parkes et al. 2008)

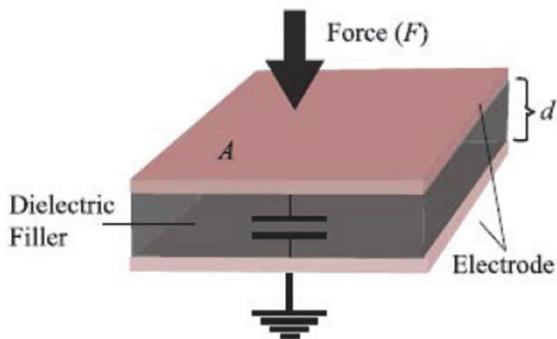


Figure 7.7. Parallel plate capacitor consisting of two parallel plates of area A separated by distance d (Dahiya and Valle 2013)

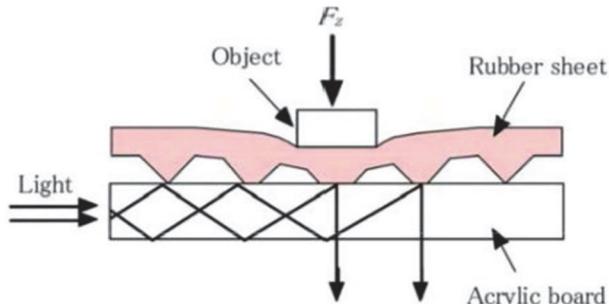


Figure 7.8. Principle of optical tactile sensor (Ohka 2007)

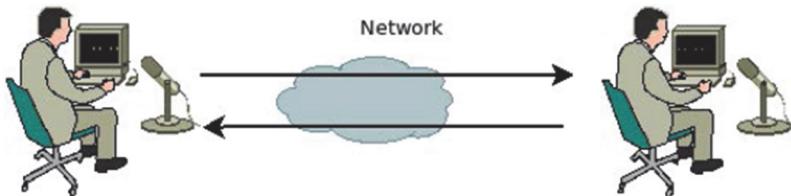


Figure 7.11. Conversation in a video teleconferencing is two times unidirectional

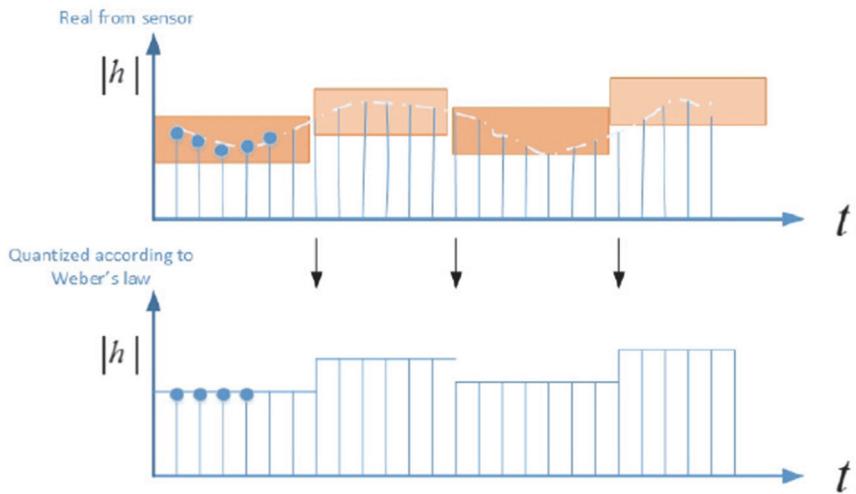


Figure 7.12. Perceptual deadband compression

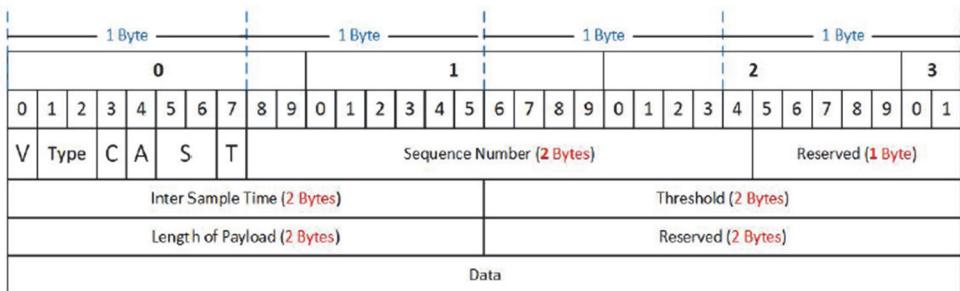


Figure 7.17. The frame of HoIP protocol (Gokhale et al. 2013)

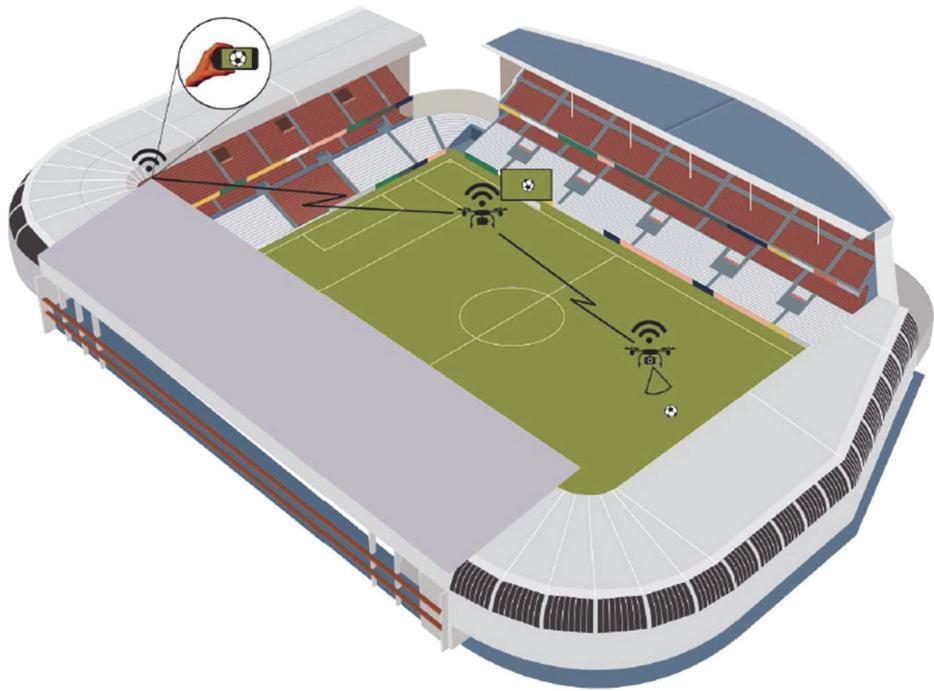


Figure 8.1. A subset of two robots in a WNR that is used to relay the video of a sporting event to a spectator too far away to receive it in HD from the filer UAV using a second one, a relayer. The filer UAV is capable of tracking the sporting event and the relayer UAV is capable of placing itself in a position to relay the video, in HD, to all the spectators on its side



Figure 8.2. Example of a WNR for Mobile Cellular Infrastructure inside its Mission Area. The single UAV with its R^i coverage tries to maximize the fleet Coverage Area by moving inside Area-X while still keeping the formation

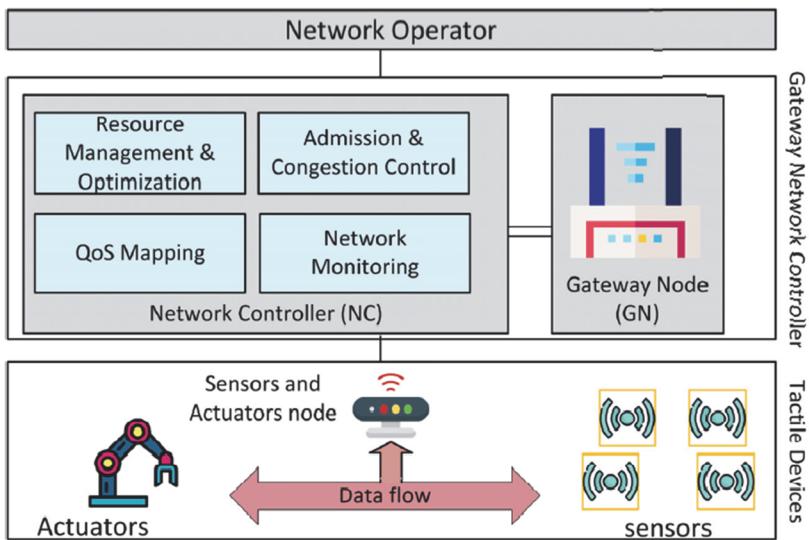


Figure 9.1. GNC architecture

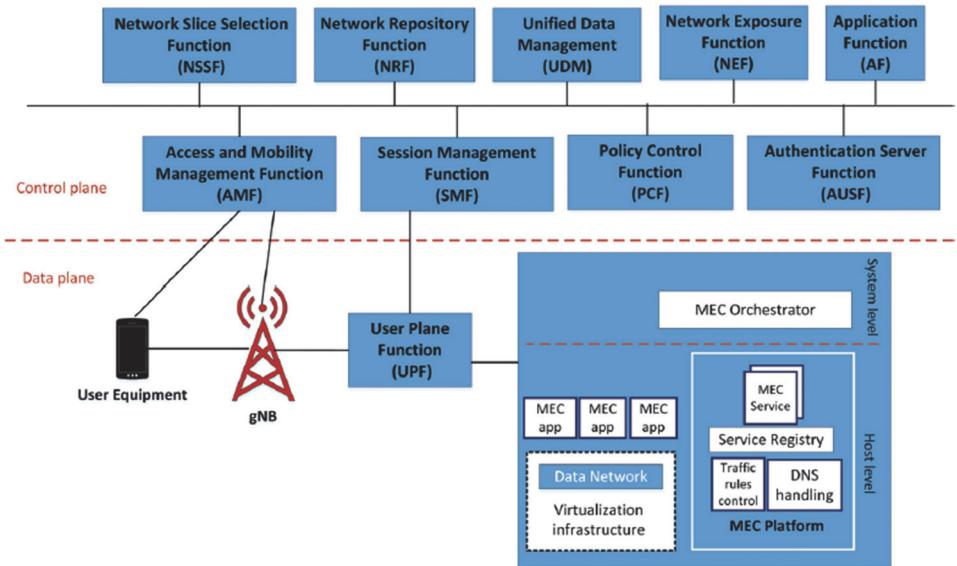


Figure 9.2. MEC integrated with 5G

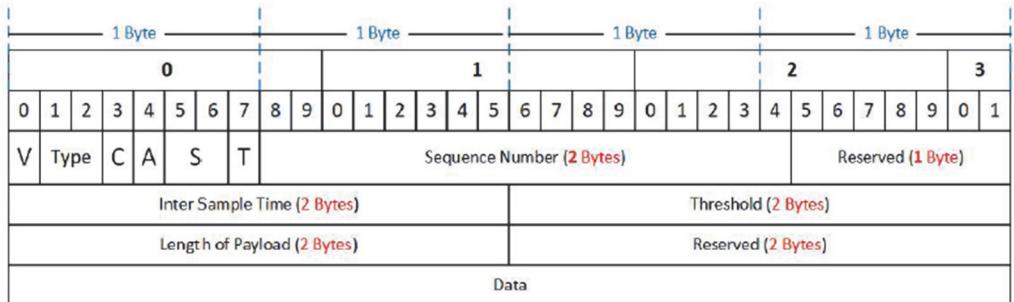


Figure 9.5. HolP in the protocol stack

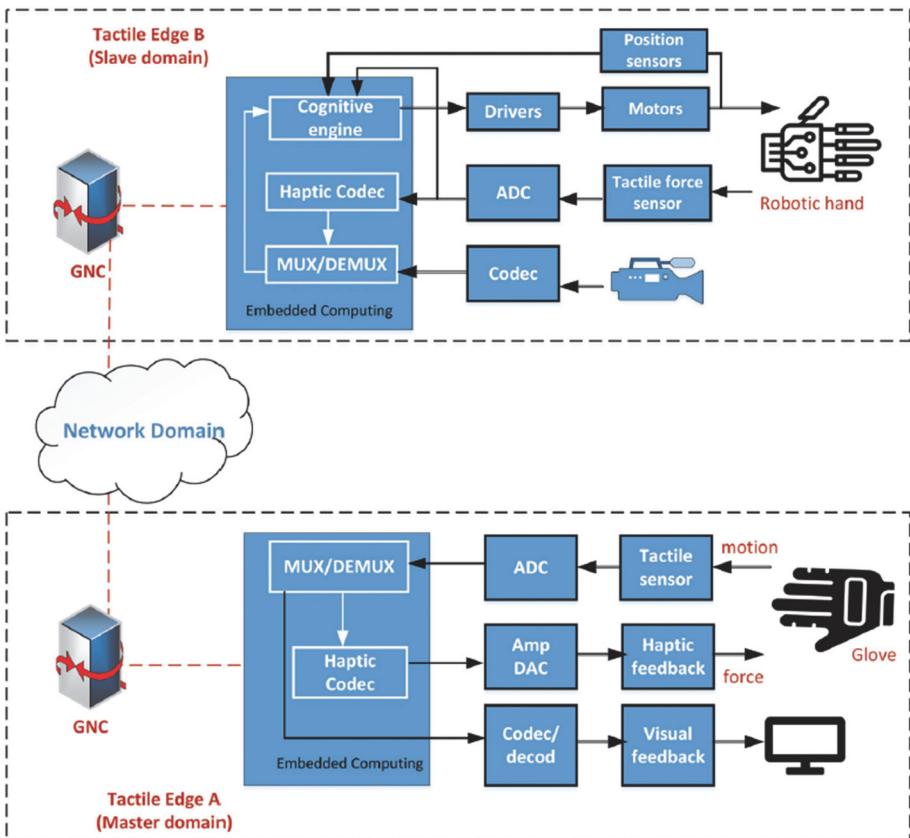


Figure 9.6. Teleoperation system design

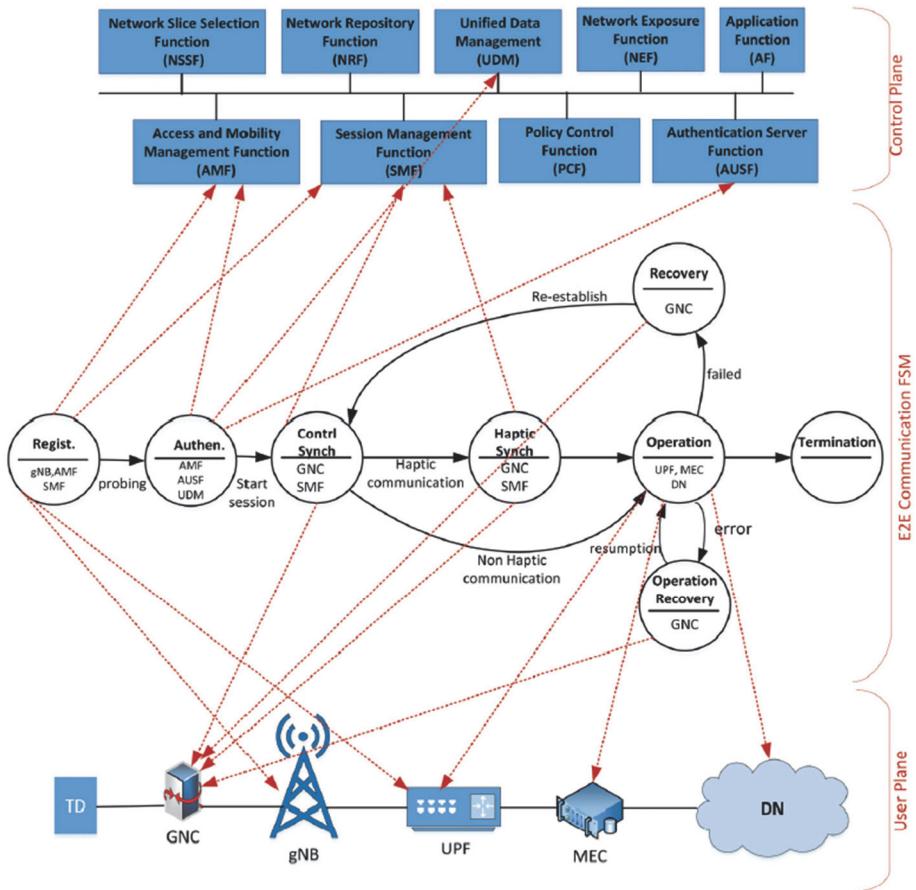


Figure 9.7. Moore FSM for E2E communication in an integrated 5G and IEEE 1918.1 architecture

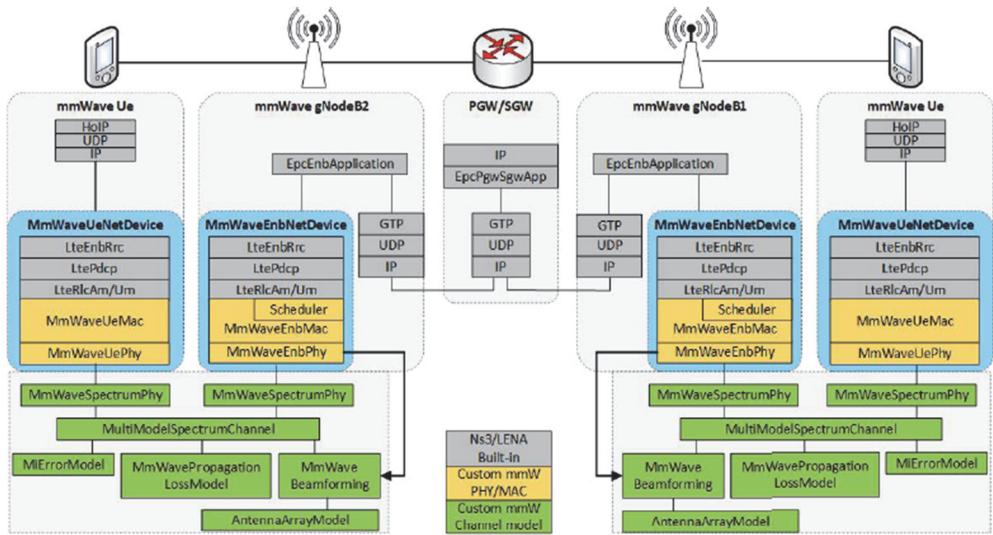


Figure 9.12. End-to-end network architecture

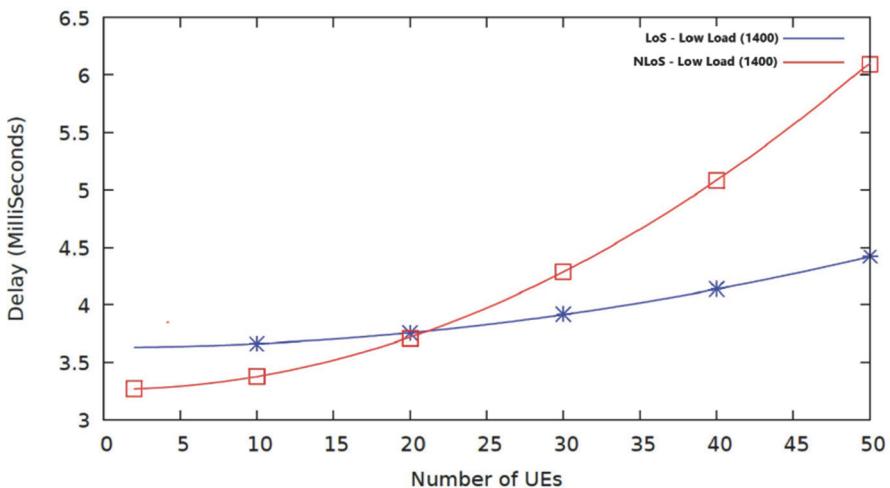


Figure 9.13. Delay versus number of UEs for low load (LoS and NLoS)

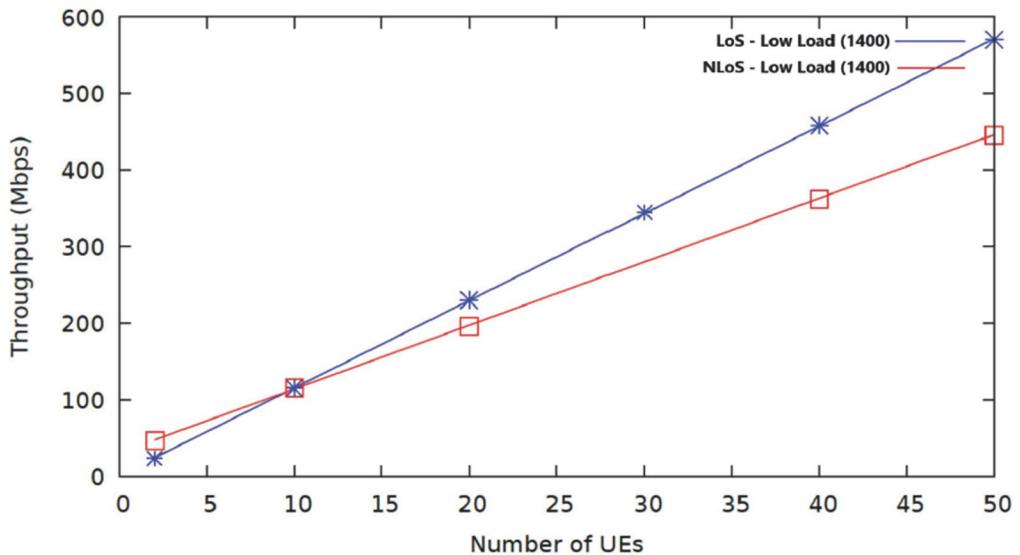


Figure 9.14. End-to-end network architecture

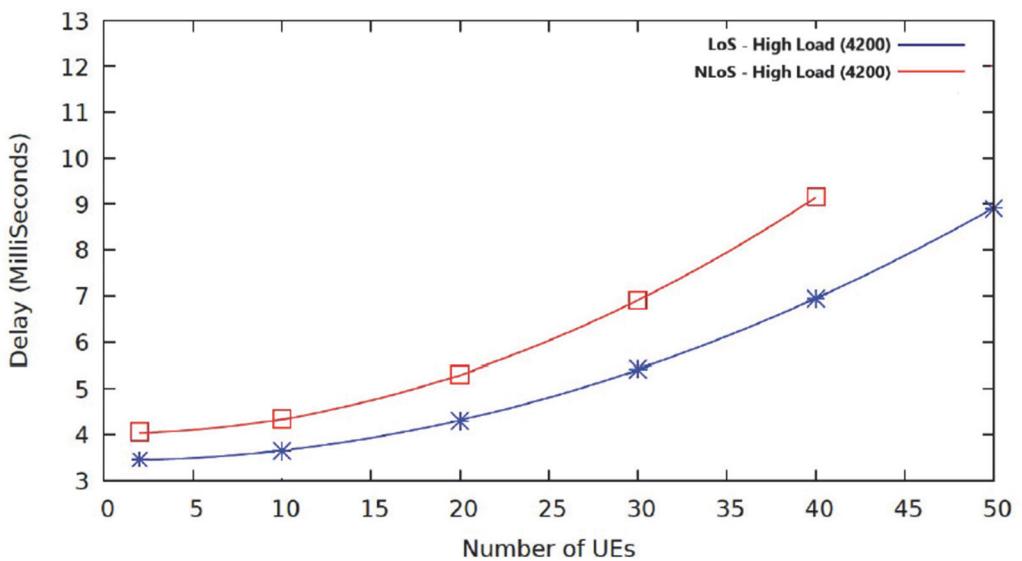


Figure 9.15. Delay versus number of UEs for high load (LoS and NLoS)

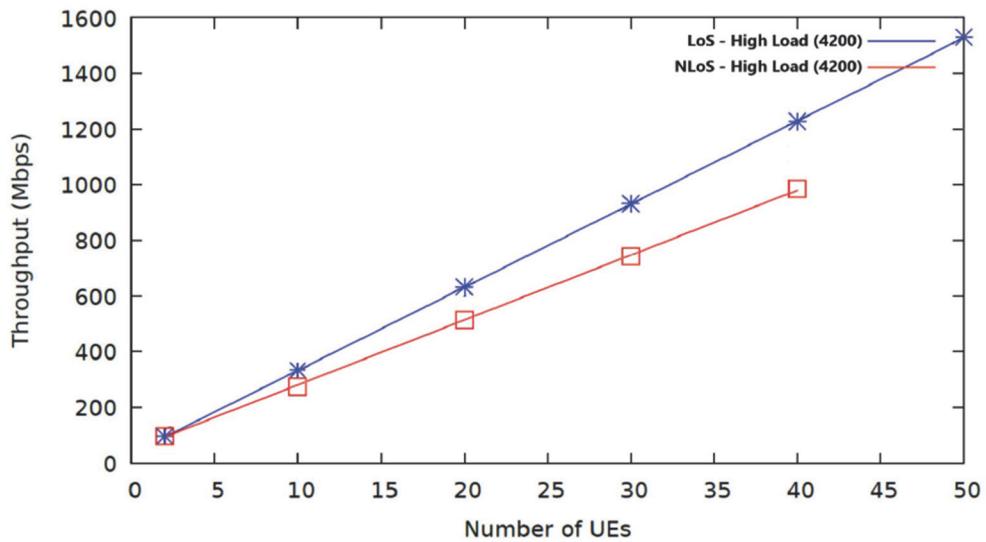


Figure 9.16. Throughput versus number of UEs for high load (LoS and NLoS)

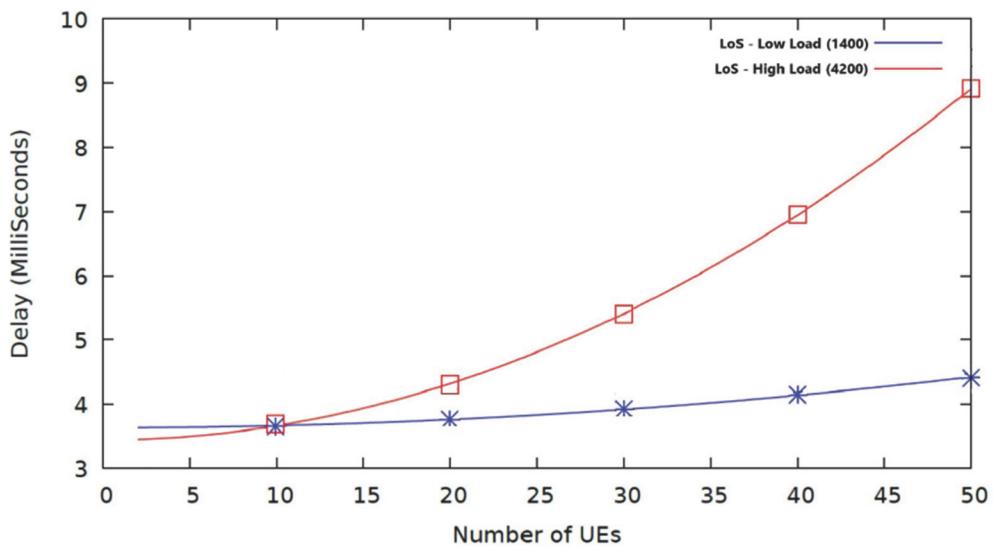


Figure 9.17. Delay versus number of UEs for LoS (low load and high load)

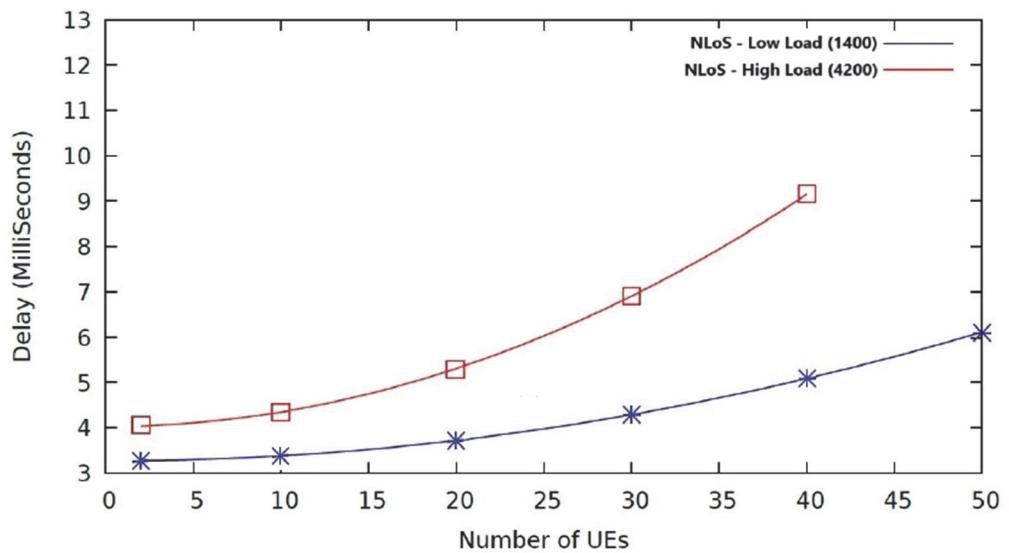


Figure 9.18. Delay versus number of UEs for NLoS (low load and high load)

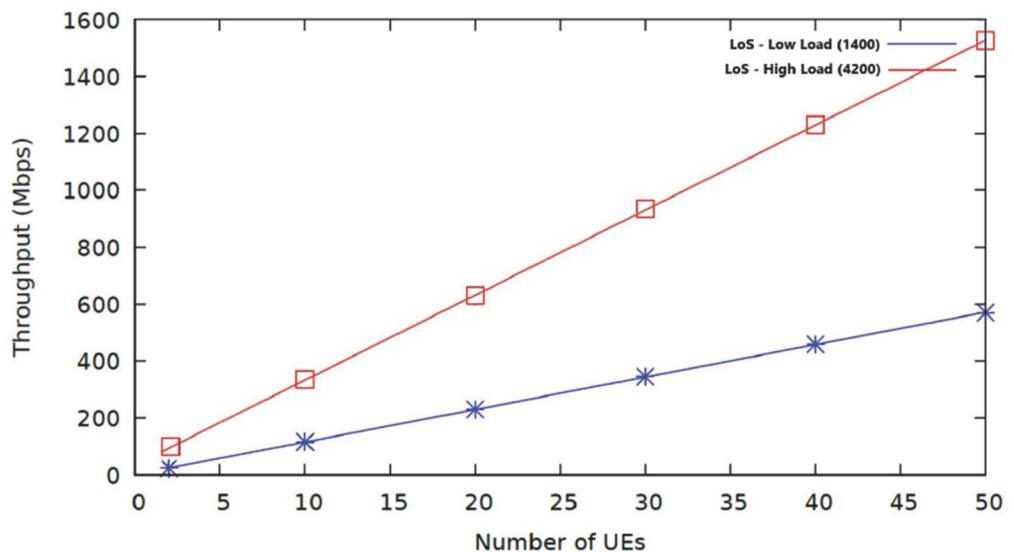


Figure 9.19. Throughput versus number of UEs for LoS (low load and high load)

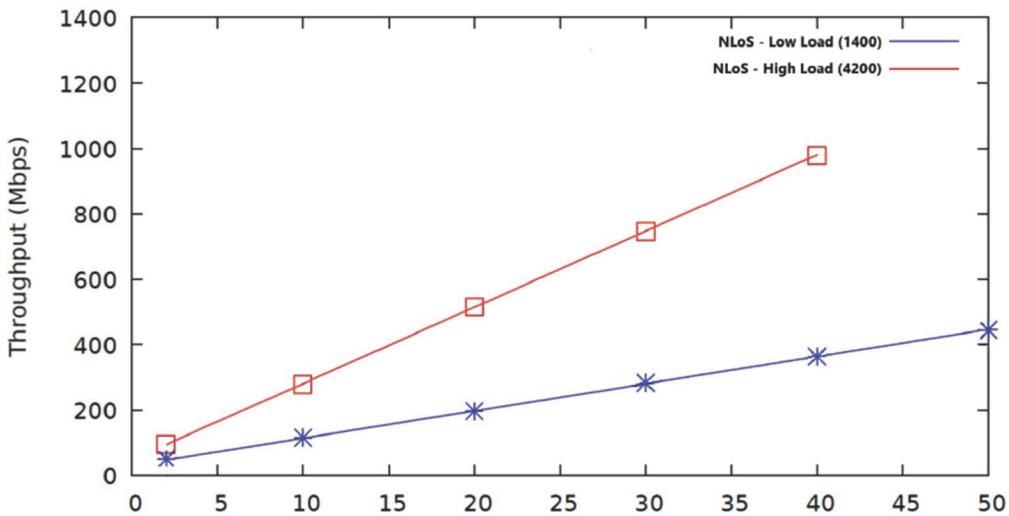


Figure 9.20. Throughput versus number of UEs for NLoS (low load and high load)